



## Material Content Data Sheet



<b>Sales Product Name</b>		ESD114-U1-02ELS E6327		<b>Issued</b>		27. September 2017		
<b>MA#</b>		MA001240254						
<b>Package</b>		PG-TSSLP-2-3		<b>Weight*</b>		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.17		1670	
	noble metal	gold	7440-57-5	0.001	0.65		6469	
	inorganic material	silicon	7440-21-3	0.010	4.79	5.61	47945	56084
leadframe	non noble metal	nickel	7440-02-0	0.108	51.71	51.71	517148	517148
wire	non noble metal	copper	7440-50-8	0.001	0.68	0.68	6770	6770
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1885	
	plastics	epoxy resin	-	0.011	5.46		54600	
	inorganic material	silicondioxide	60676-86-0	0.067	32.01	37.66	320071	376556
leadfinish	noble metal	gold	7440-57-5	0.004	1.76	1.76	17645	17645
plating	noble metal	palladium	7440-05-3	0.001	0.61		6119	
	noble metal	gold	7440-57-5	0.004	1.97	2.58	19678	25797
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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